

Name: Mini Heating Platform

Model:VB-215A

Temp. Range: 160~250°C

N.W.: 90.4g

Work area□ 20\*18.5mm

Product size: 70.5x76.7x21.6mm

Application: Suitable for 99% of chips on the market, universal for removing glue and tin from various types of iphones, huawei and other mobile phone CPU

Type-C USB

# Mini Heating Platform

160°C~250°C Adjustable

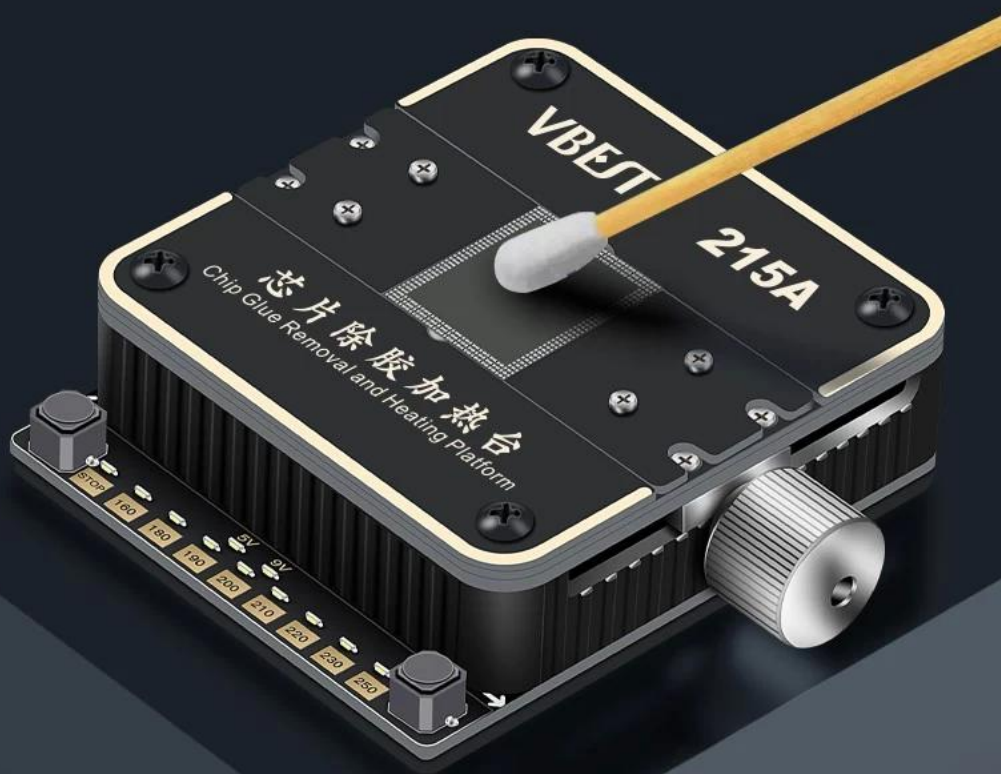
No need for heat gun or soldering iron heating, no need for soldering wick  
No damage to solder pads and paint



# No need for Soldering Wick



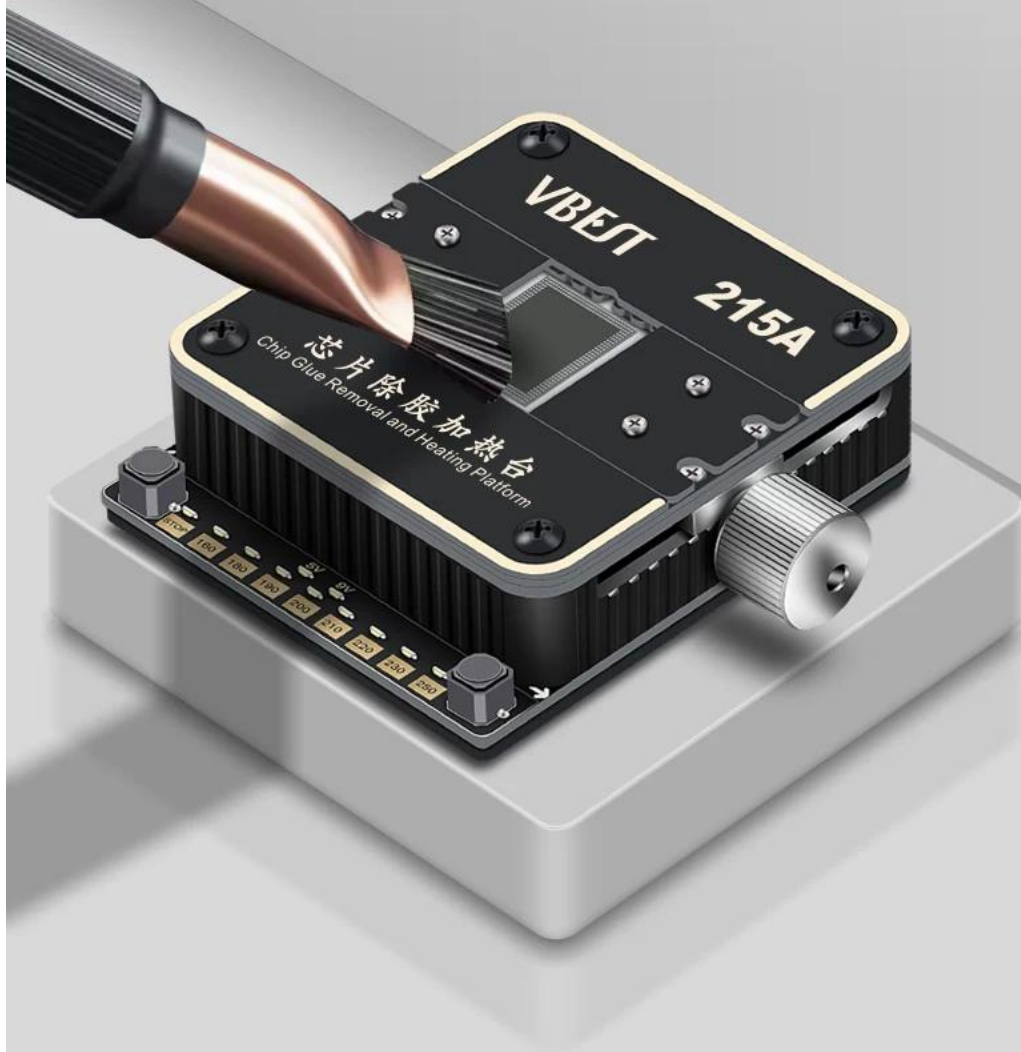
After heating to the set temperature, use a cotton swab to clean up the residual tin. No damage to the solder pad paint, no need for soldering wick wiping to wear out the chip



## Heating to remove tin



Turn on the heating platform and heating to the preset temperature, you can use a brush or cotton swab to remove residual tin without soldering wick. Gently wipe to remove tin and glue easily.



160°C~250°C

## Constant Temperature Heating



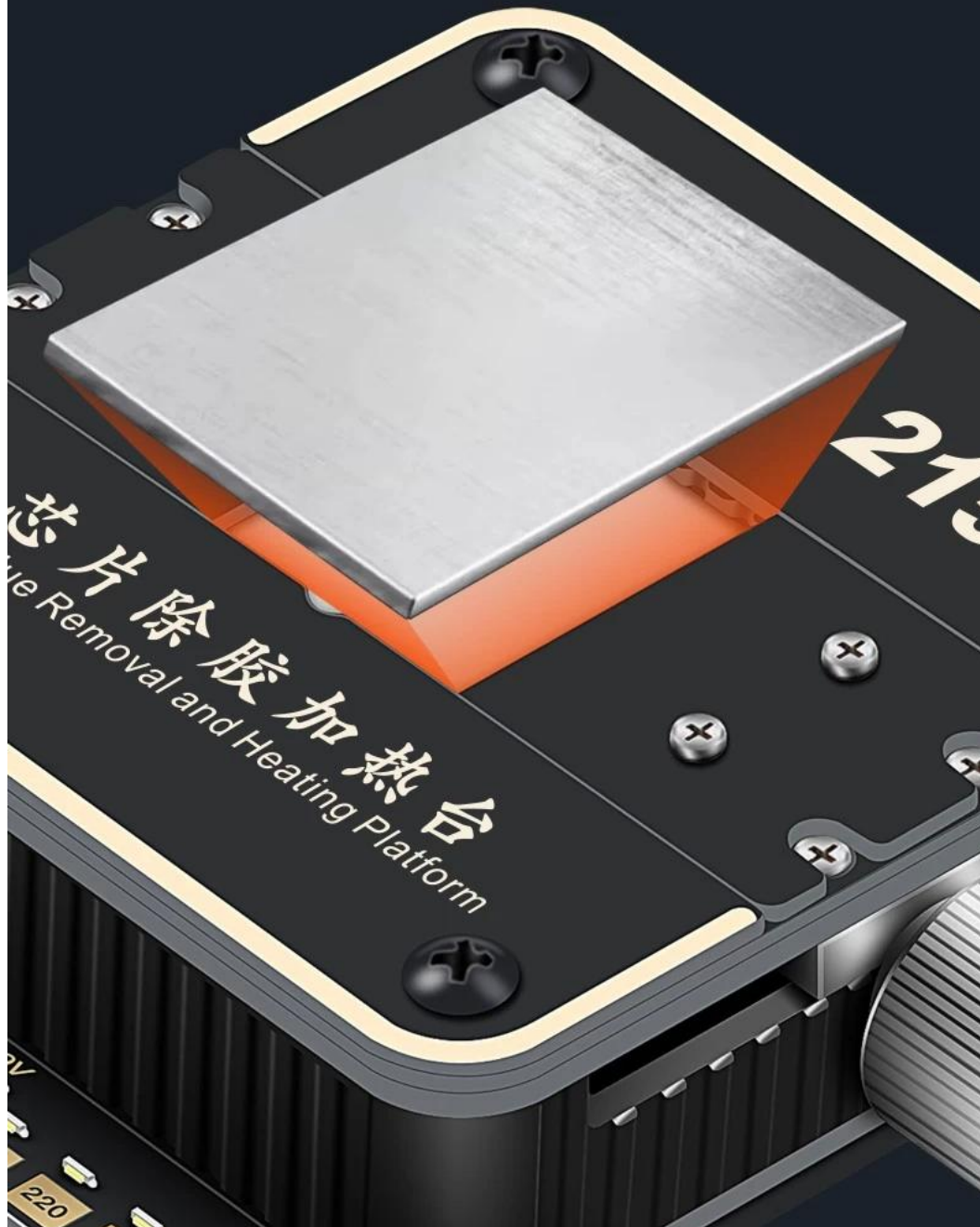
During heating operation, the temperature can be adjusted between 160~250 °C  
Effectively prevent chip burnout caused by high temperature or improper adjustment



# Low Voltage Heating Plate



Fast heating, no leakage, anti-static, safer heating  
Built in professional tuning curve, no need to worry about  
chip damage caused by thermal stress



# Flexible hidden screw rod



Hidden screw rod, flexible and clever, extendable  
and fixed clamping the chips  
Prevent residue from falling into the screw,  
making it more durable



# Uniform Heating



No need for heat gun heating, it is safer to scrape glue  
at a temperature 100 °C lower than the heat gun

No need to repeatedly scrape with a soldering iron,  
no damage to the solder pads



**Temperature adjustable**

**160~250°C**

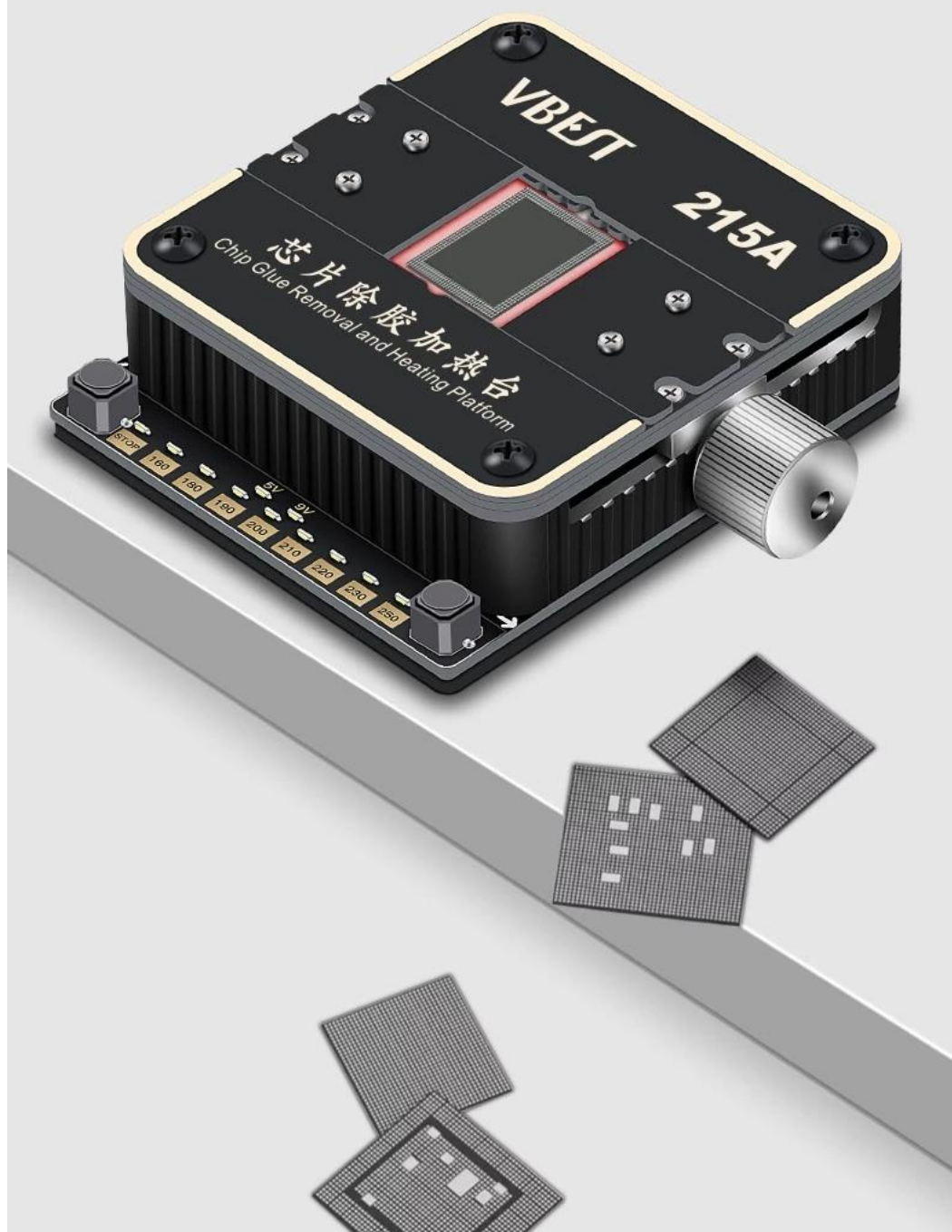


# Suitable for 99% of chips



Work area: 20mm×18.5mm (Max)

Support multi generation iPh, Huawei phone CPU chips  
and hard drives





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\* The above dimensions are measured manually and may have about 1-2mm error